

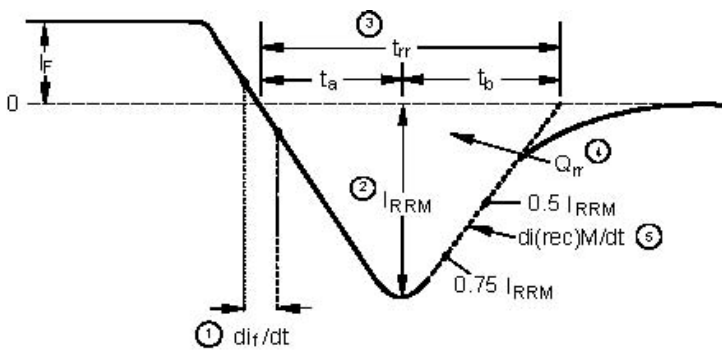


PRELIMINARY SPECIFICATION №141. **ULTRAFAST DIODE KD-0560UF.**

 VSP MIKRON 	5A/600V. Die Size-75*76mil.			
	Electrical Characteristics	Symbol	Unit	Spec. limit
Breakdown Voltage @ $I_R=0,10\text{mA}$	V_B	V	600	620
Average Rectified Forward Current	$I_{F(AV)}$	A	5,0	-
DC Forward Voltage @ $25^\circ\text{C}, I_F=5,0\text{A}$	V_F	V	1,50	1,45
Maximum Reverse Current @ $25^\circ\text{C}, V_R=600\text{V}$ @ $125^\circ\text{C}, V_R=600\text{V}$	I_R	MA	0,010 0,500	0,009 0,450
Reverse Recovery Time, $I_F=1\text{A}, V_R=30\text{V}, dI_F/dt=100\text{A/uS.}$	t_{rr}	nS	60	55
Operating Junction Temperature	T_J	$^\circ\text{C}$	175	



- di_F/dt - Rate of change of current through zero crossing
- I_{RRM} - Peak reverse recovery current
- t_{rr} - Reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current
- Q_{rr} - Area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$
- $di_{(rec)M}/dt$ - Peak rate of change of current during t_b portion of t_{rr}

DIM	ITEM	μm
A_x A_y	Die Size	1900 1940
B_x B_y	Top Metal Size	1160 1200
D	Thickness	350max.
Scribe line Width		60

Top metal: Al – for Wire Bonding.

Backside metal: Ti-Ni-Ag – for Soldering

www.vsp-mikron.com

